



Material Content Data Sheet



Sales Product Name		ICE3BR4765JZ		Issued		29. August 2013		
MA#		MA001095672						
Package		PG-DIP-7-2		Weight*		602.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.480	0.41	0.41	4119	4119
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		80	
	non noble metal	zinc	7440-66-6	0.194	0.03		322	
	non noble metal	iron	7439-89-6	3.872	0.64		6432	
wire	non noble metal	copper	7440-50-8	157.218	26.11	26.79	261146	267980
	noble metal	gold	7440-57-5	0.288	0.05	0.05	478	478
	encapsulation	organic material	carbon black	1333-86-4	1.713	0.28		2846
encapsulation	plastics	epoxy resin	-	49.690	8.25		82537	
	inorganic material	silicondioxide	60676-86-0	376.958	62.64	71.17	626144	711527
leadfinish	non noble metal	tin	7440-31-5	6.460	1.07	1.07	10730	10730
plating	noble metal	silver	7440-22-4	1.594	0.26	0.26	2648	2648
glue	plastics	epoxy resin	-	0.227	0.04		378	
	noble metal	silver	7440-22-4	1.288	0.21	0.25	2140	2518
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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